

[54] SEMICONDUCTOR HOUSING

[75] Inventor: Jerry M. Du Bois, Mesa, Ariz.

[73] Assignee: Motorola, Inc., Schaumburg, Ill.

[\*\*] Term: 14 Years

[21] Appl. No.: 649,081

[22] Filed: Sep. 10, 1984

[52] U.S. Cl. .... D13/99; D13/41

[58] Field of Search ..... D13/40, 41, 99; 361/394, 395, 399, 400, 331; 174/52 R, 52 PE, 52 S; 357/70, 72, 74

[56] References Cited

U.S. PATENT DOCUMENTS

3,340,347	9/1967	Spiegler .....	174/52 PE
3,902,148	8/1975	Drees et al. .	
3,918,084	11/1975	Schierz .	
3,946,428	3/1976	Anazawa et al. .	
4,047,197	9/1977	Schierz .	
4,067,040	1/1978	Tsuzuki et al. .	
4,079,410	3/1978	Schierz .	
4,106,052	8/1978	Schierz .	
4,213,141	5/1978	Colussi .	
4,218,724	8/1980	Kaufman .....	361/395
4,278,990	7/1981	Fichot .	
4,278,991	7/1981	Ritchie et al. .	
4,340,900	7/1982	Goronkin .	

FOREIGN PATENT DOCUMENTS

2607083	9/1977	Fed. Rep. of Germany .....	174/525
---------	--------	----------------------------	---------

OTHER PUBLICATIONS

IBM Technical Disclosure Bulletin, vol. 21, #1, 6-1978, pp. 99-100, Circuit Chip Support Assembly, Coombs & Larnerd.

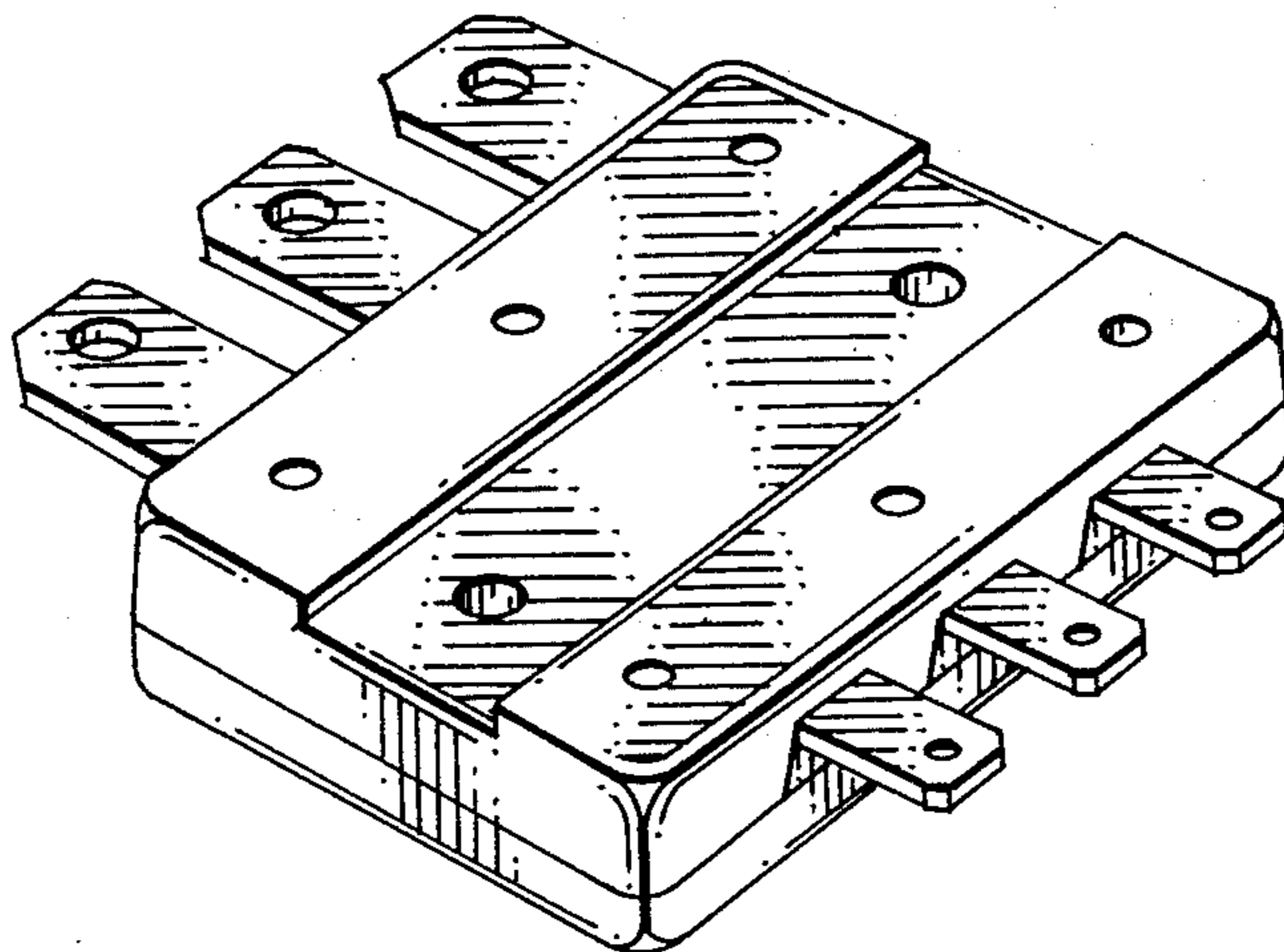
Primary Examiner—Susan J. Lucas  
Attorney, Agent, or Firm—Robert Handy

[57] CLAIM

The ornamental design for a semiconductor housing, as shown and described.

DESCRIPTION

FIG. 1 is a right side, top and front perspective view of a semiconductor housing showing my new design; FIG. 2 is a top plan view thereof on a reduced scale; FIG. 3 is a bottom plan view thereof on a reduced scale; FIG. 4 is a left side elevational view thereof on a reduced scale; FIG. 5 is a right side elevational view thereof on a reduced scale; FIG. 6 is a front elevational view thereof on a reduced scale; FIG. 7 is a rear elevational view thereof on a reduced scale; FIG. 8 is a top plan view of second embodiment of my new design, the second embodiment being identical to the first except for the number of leads on the right hand side; FIG. 9 is a bottom plan view thereof; FIG. 10 is a top plan view of a third embodiment of my new design, the third design being identical to the first embodiment except for the shape of the two leads on the left hand side; FIG. 11 is a bottom plan view thereof; FIG. 12 is a right side, top and front perspective view of a fourth embodiment of my new design; FIG. 13 is a top plan view thereof on a reduced scale; FIG. 14 is a front elevational view thereof on a reduced scale; FIG. 15 is a left side elevational view thereof on a reduced scale; FIG. 16 is a right side, top and front perspective view of a fifth embodiment of my new design, the fifth embodiment being identical to the first embodiment except for the flat top surface; FIG. 17 is a right side, top and front perspective view of a sixth embodiment of my new design; FIG. 18 is a top plan view thereof on a reduced scale; FIG. 19 is a bottom plan view thereof on a reduced scale; FIG. 20 is a left side elevational view thereof on a reduced scale; FIG. 21 is a right side elevational view thereof on a reduced scale.



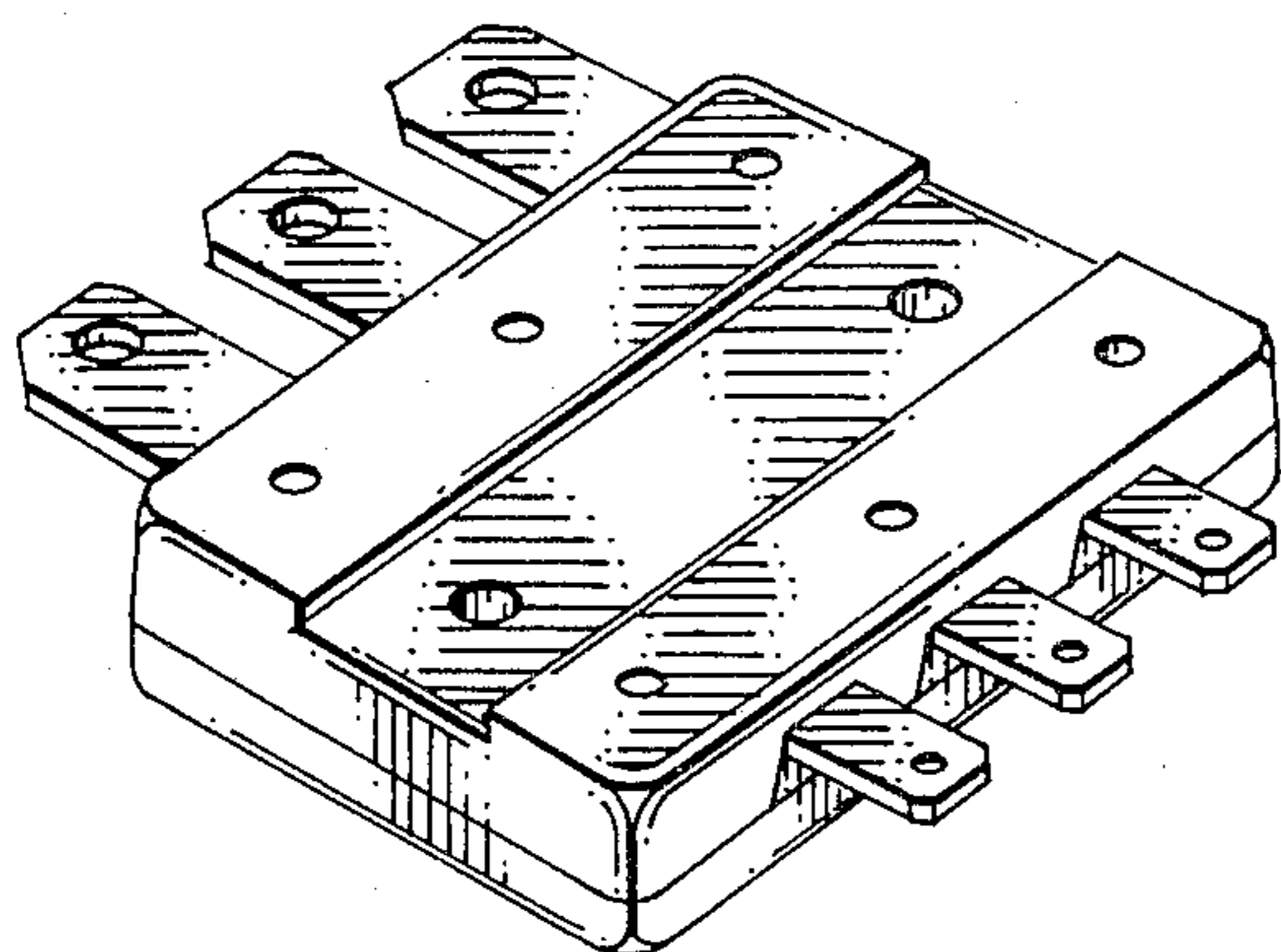


FIG. 1

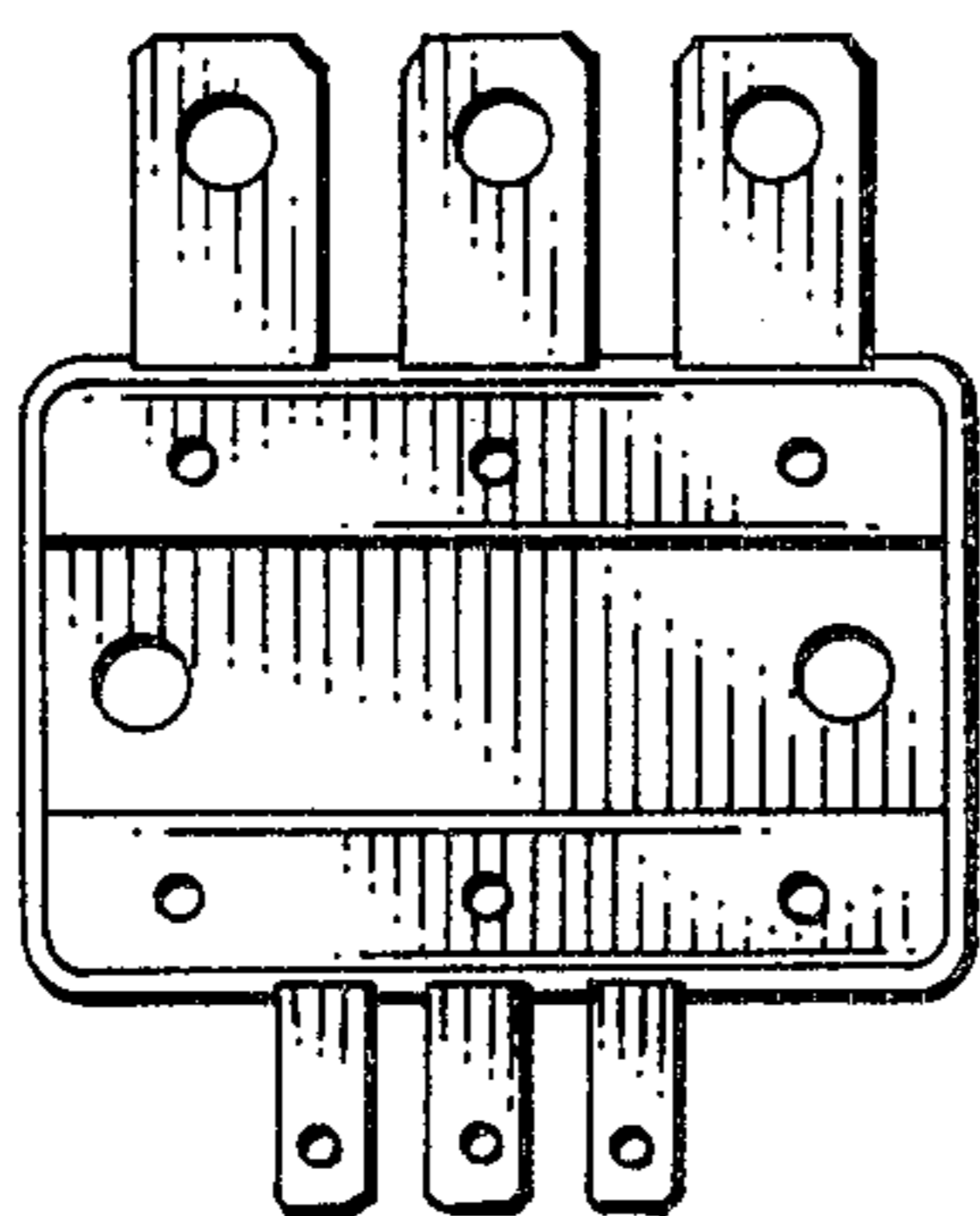


FIG. 2

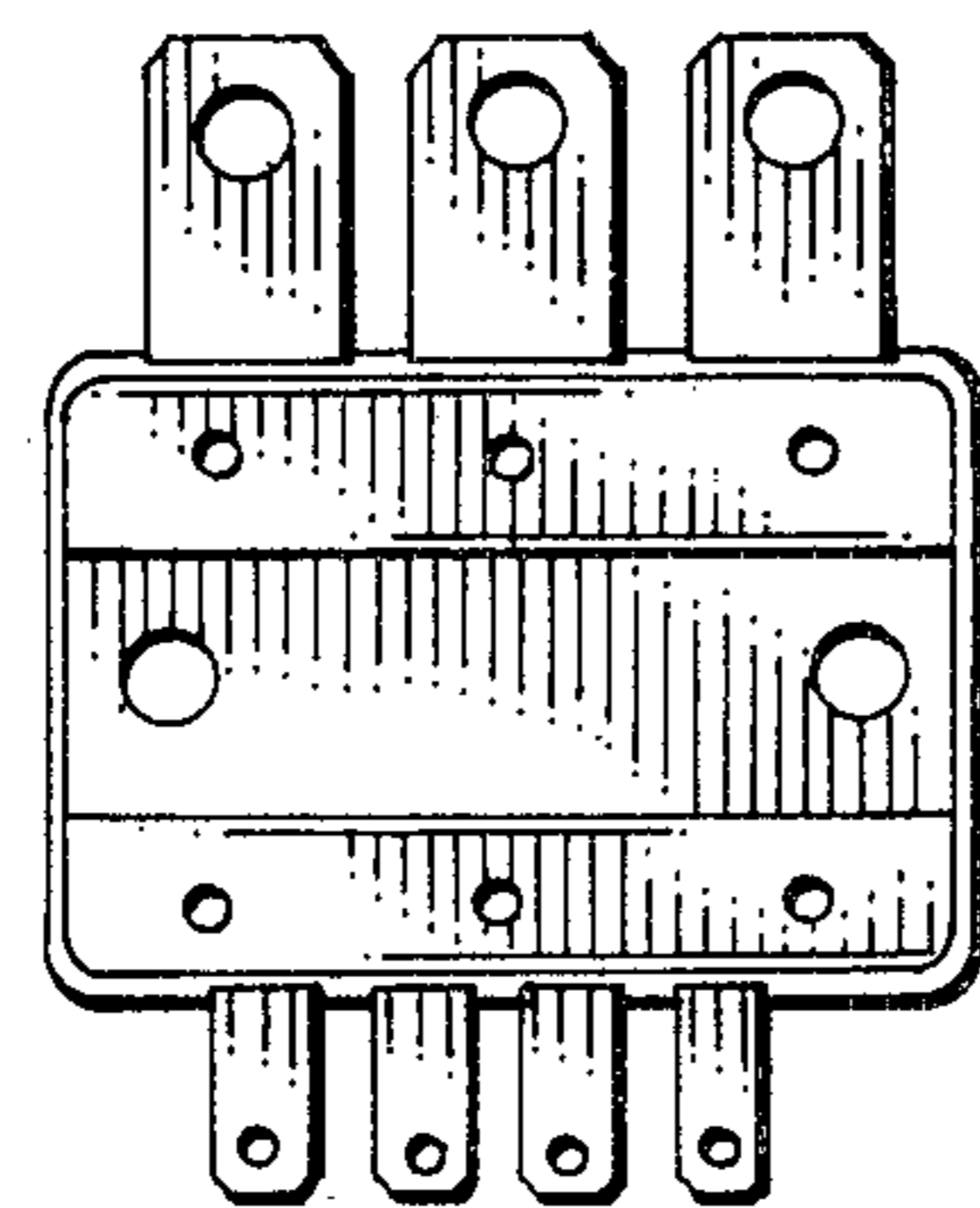


FIG. 8

FIG. 4

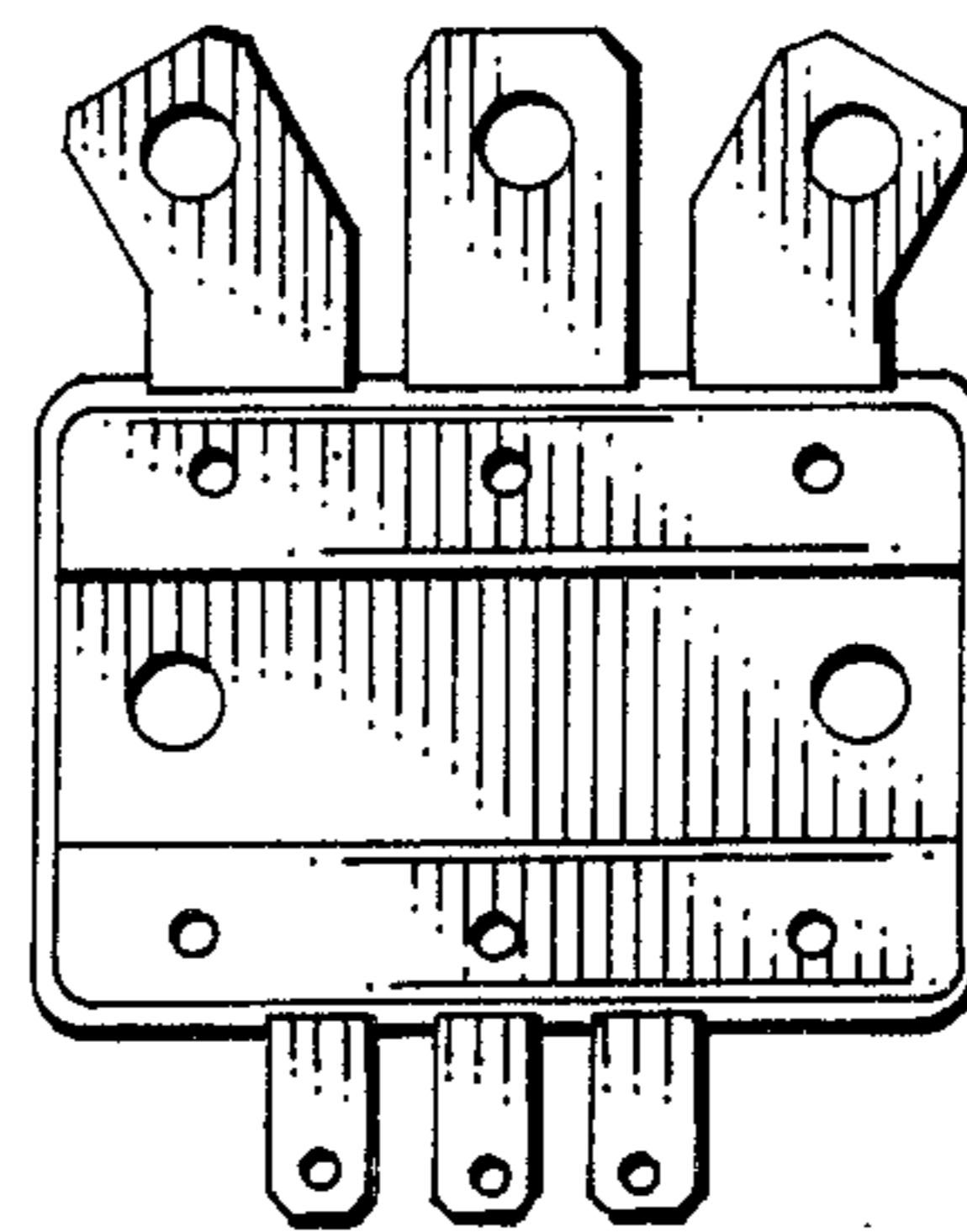


FIG. 10

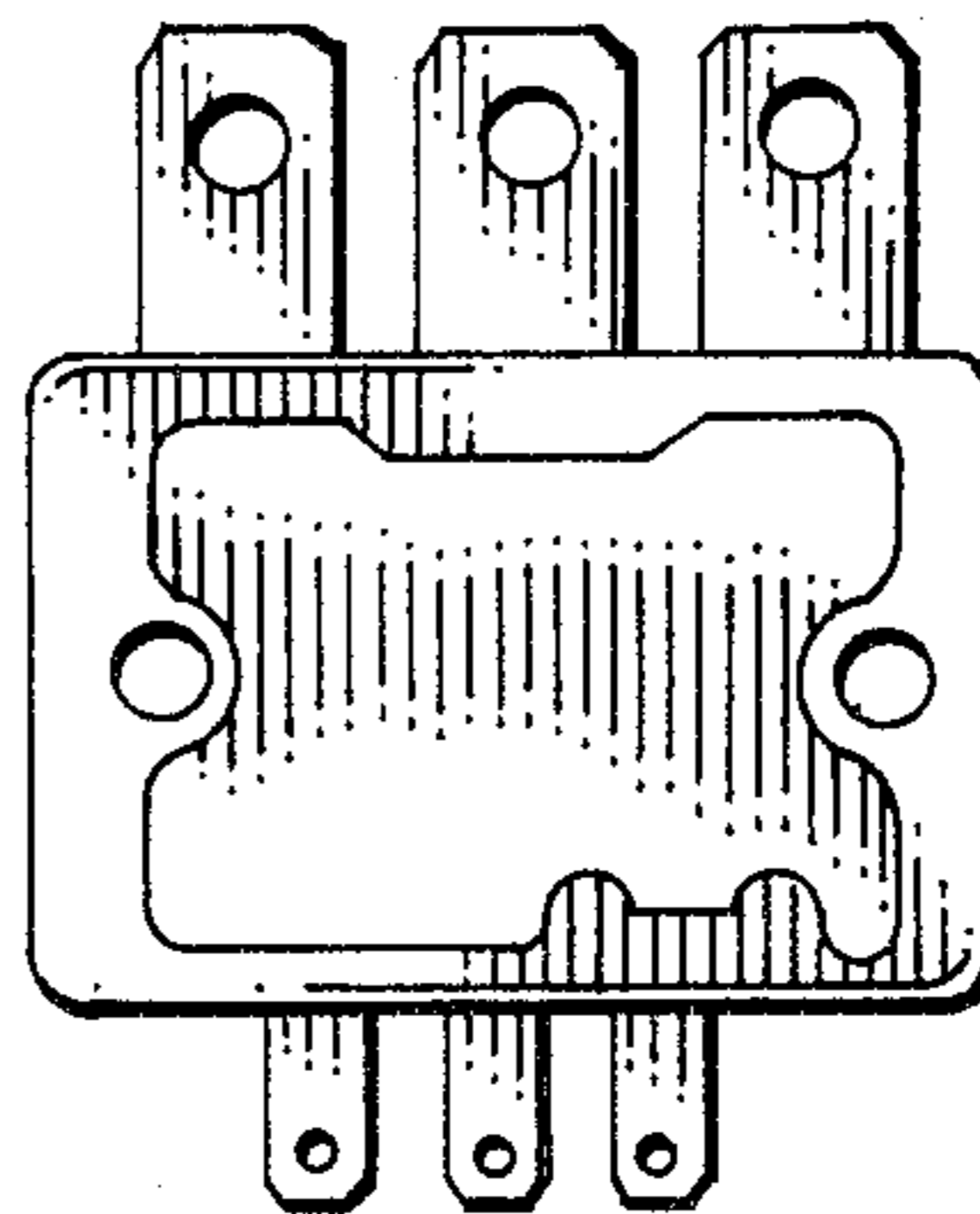


FIG. 3

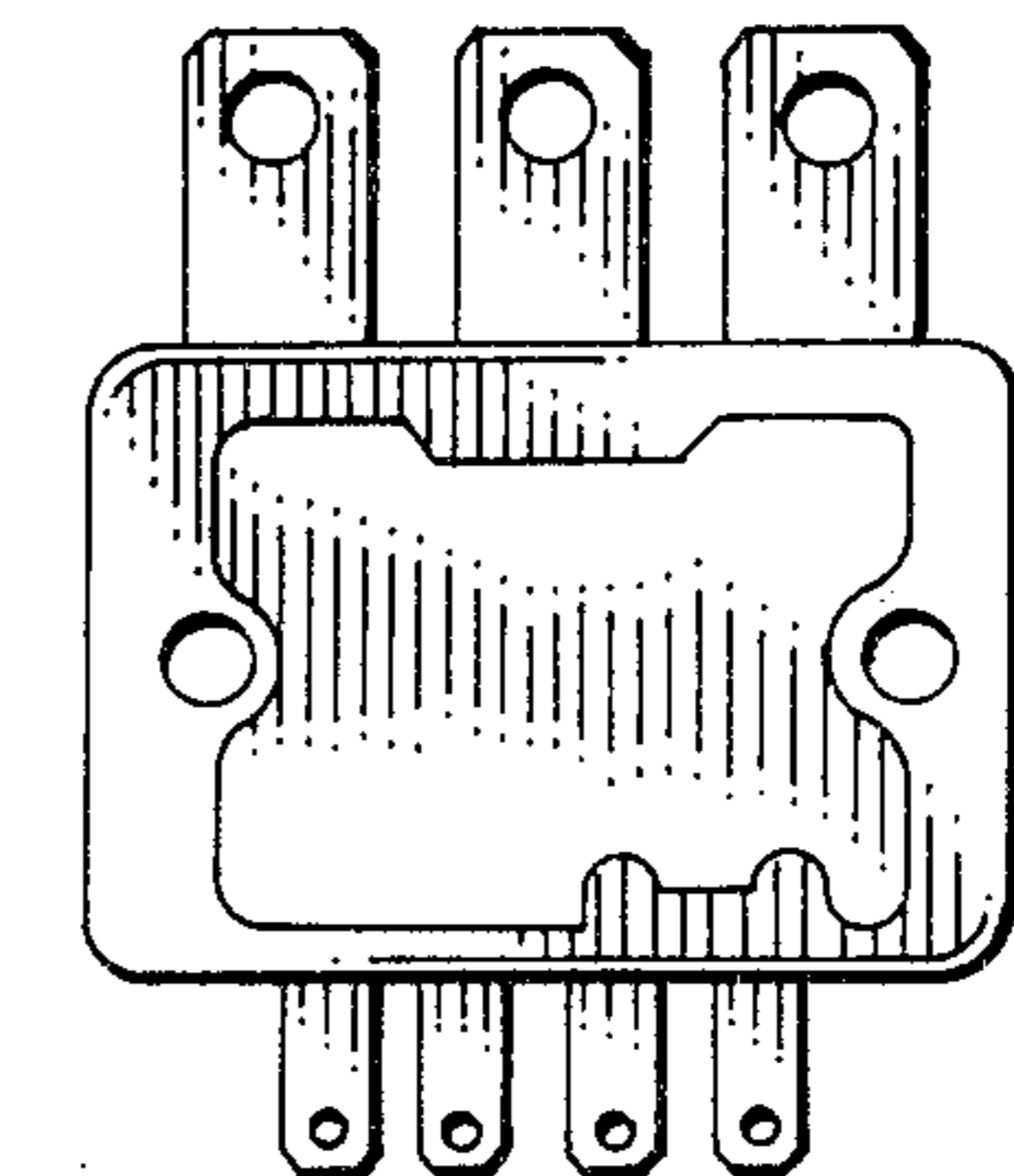


FIG. 9



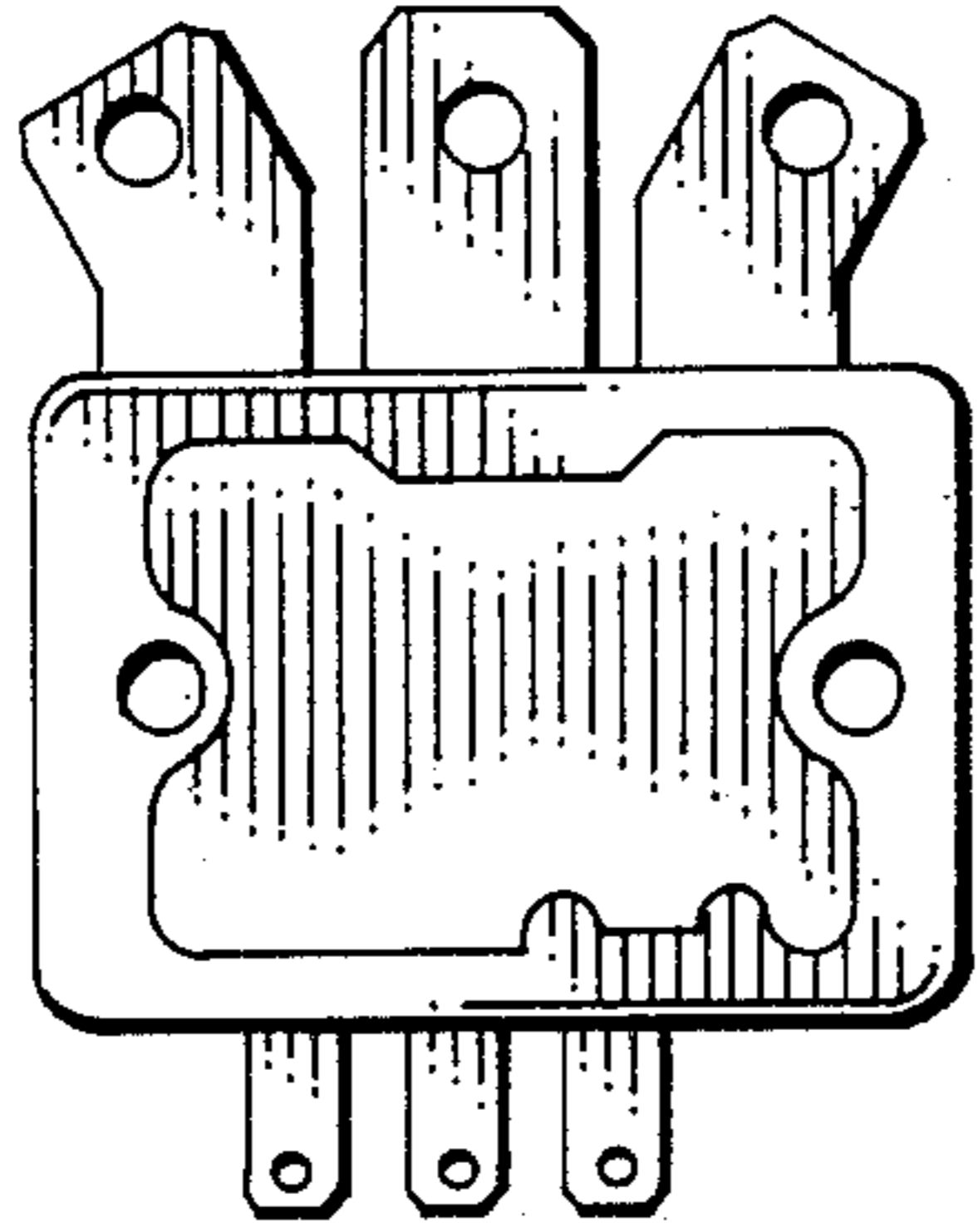


FIG. 11

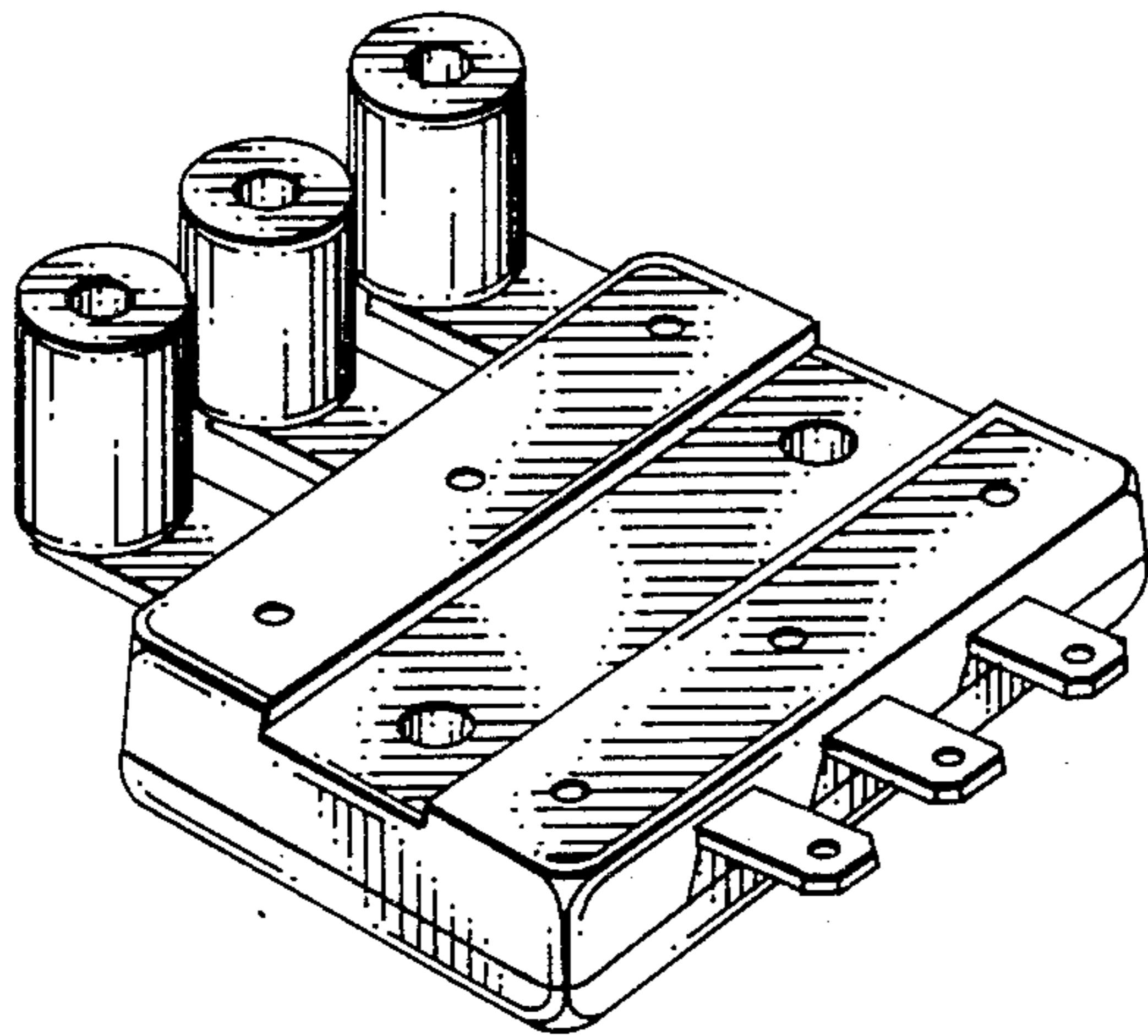


FIG. 12

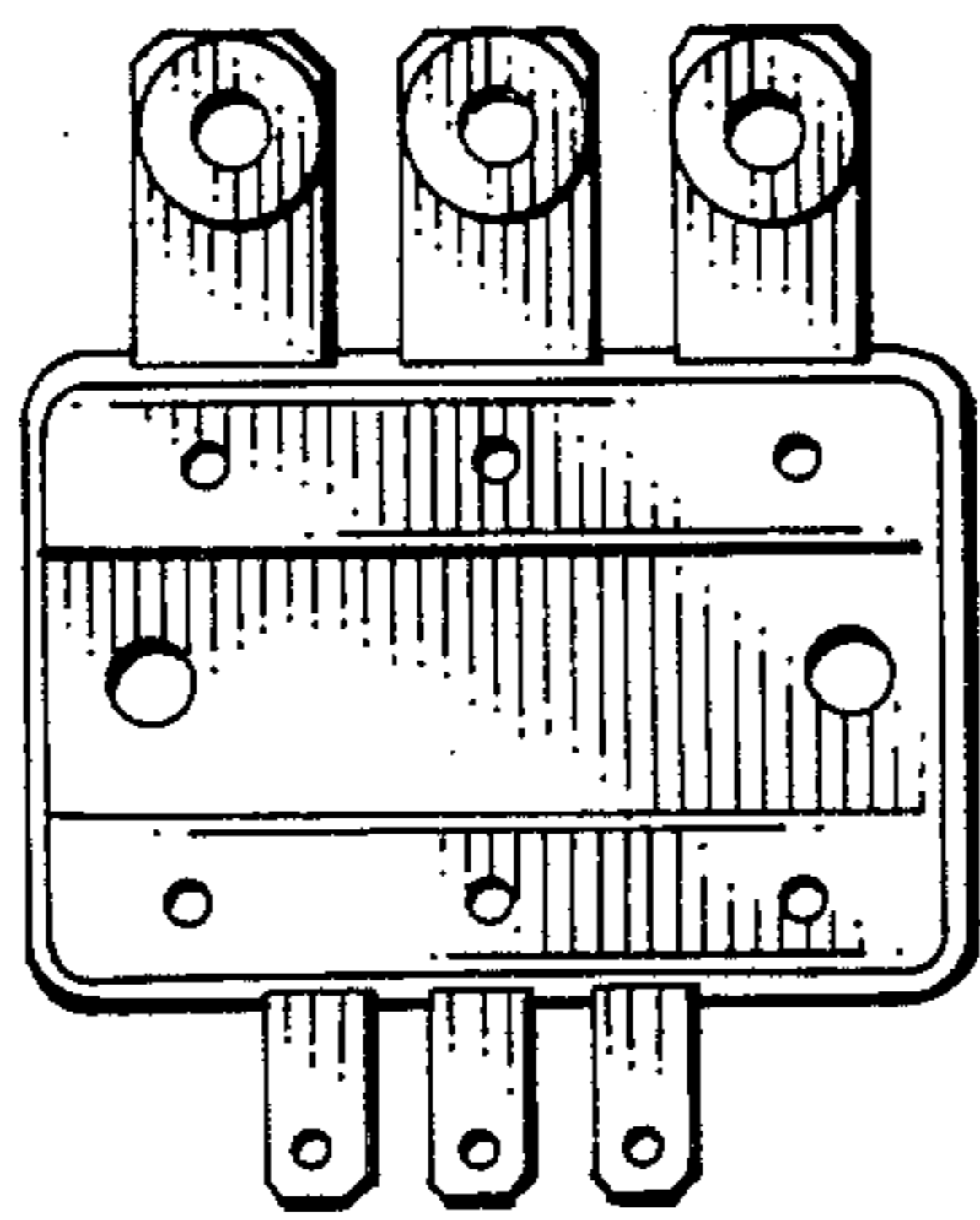


FIG. 13



FIG. 5

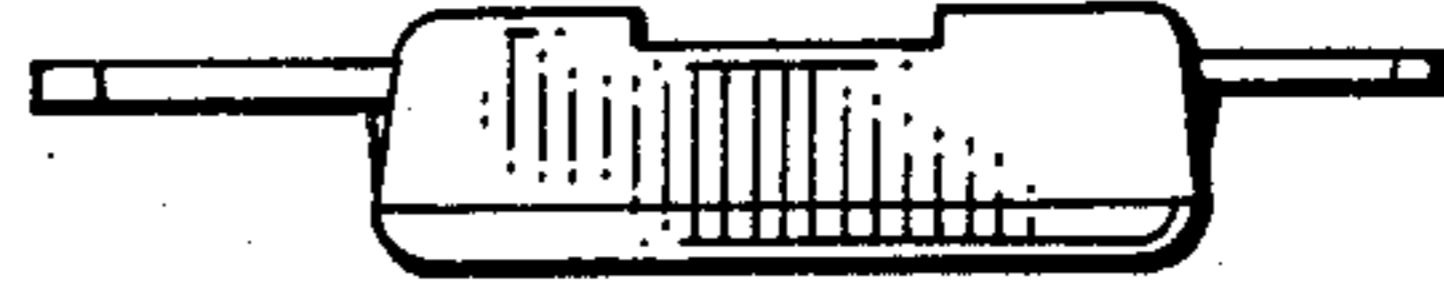


FIG. 6



FIG. 14

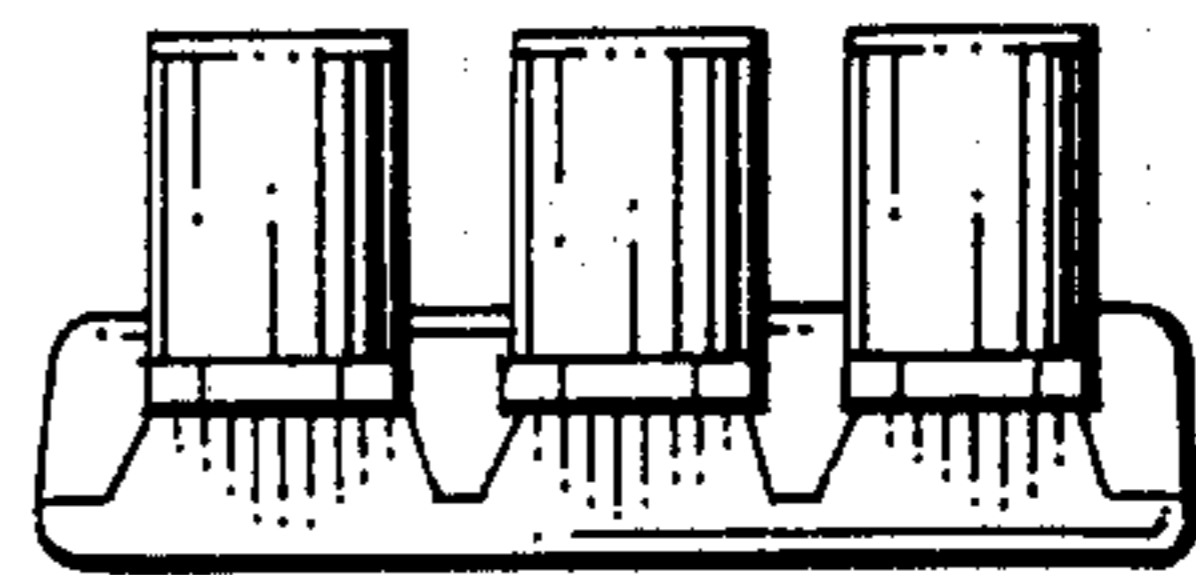


FIG. 15

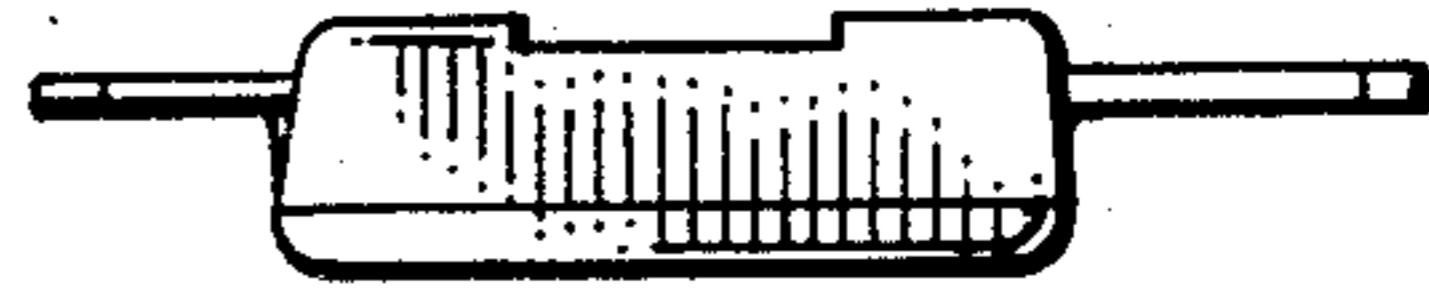


FIG. 7

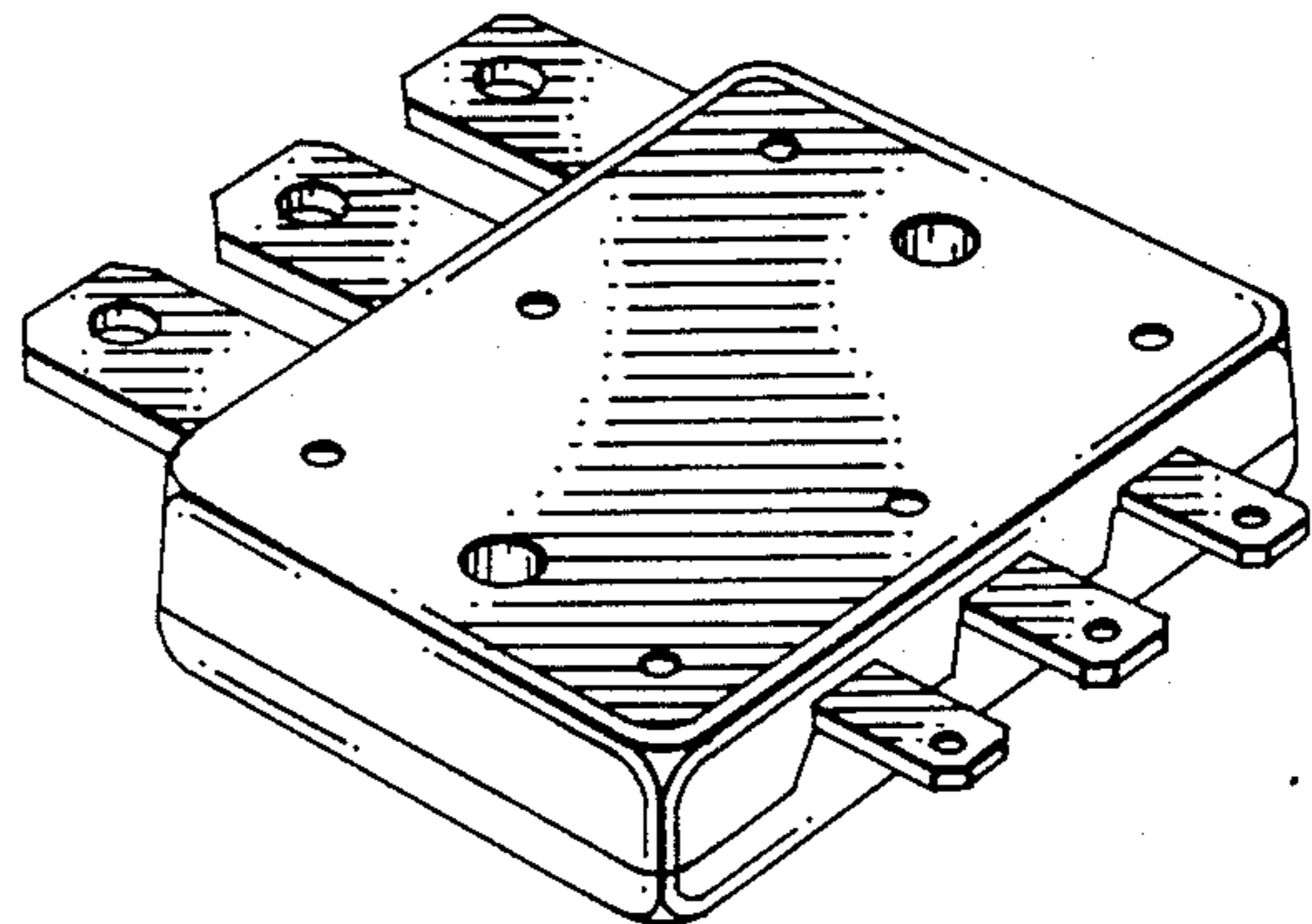


FIG. 16

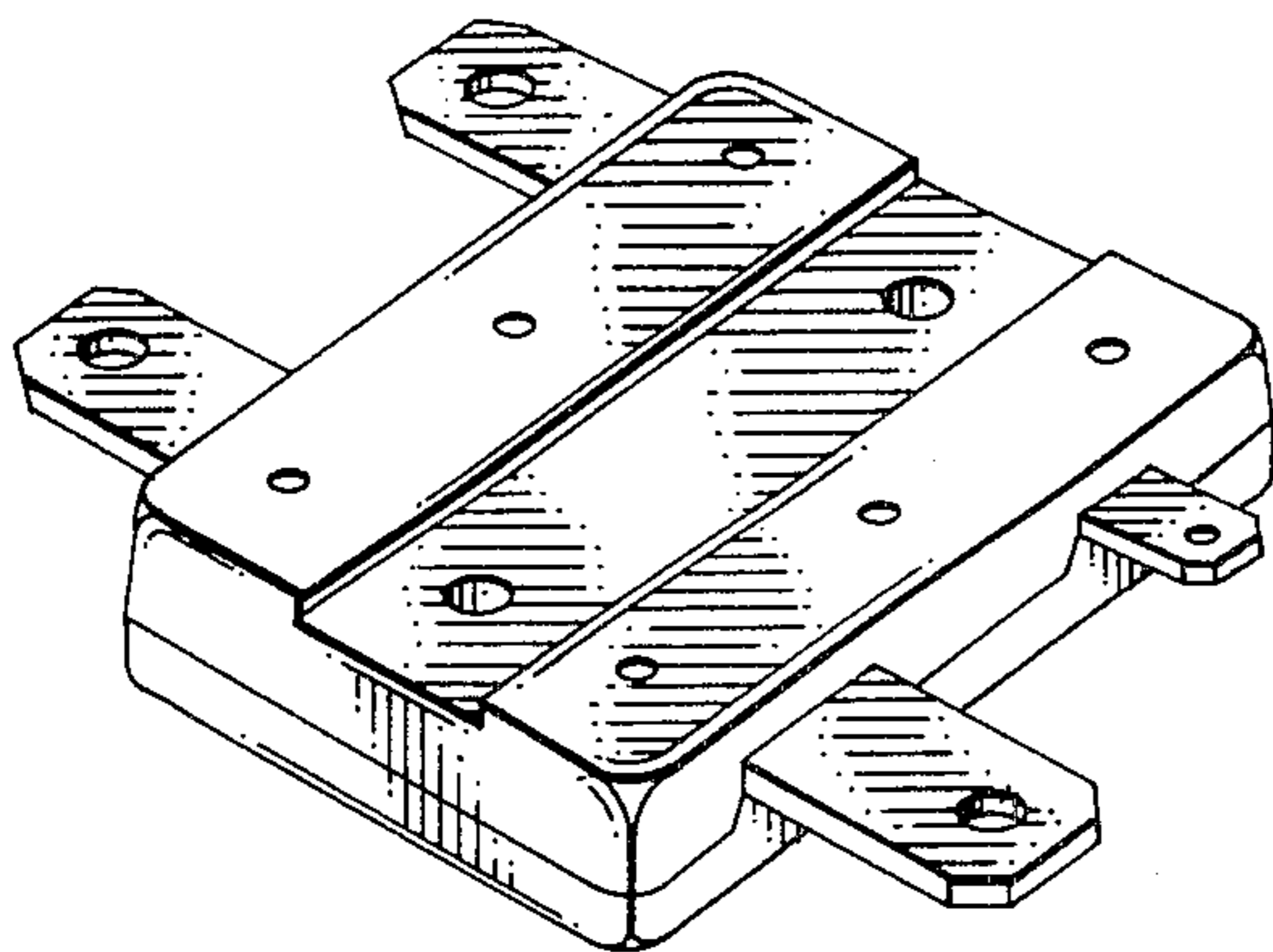


FIG. 17

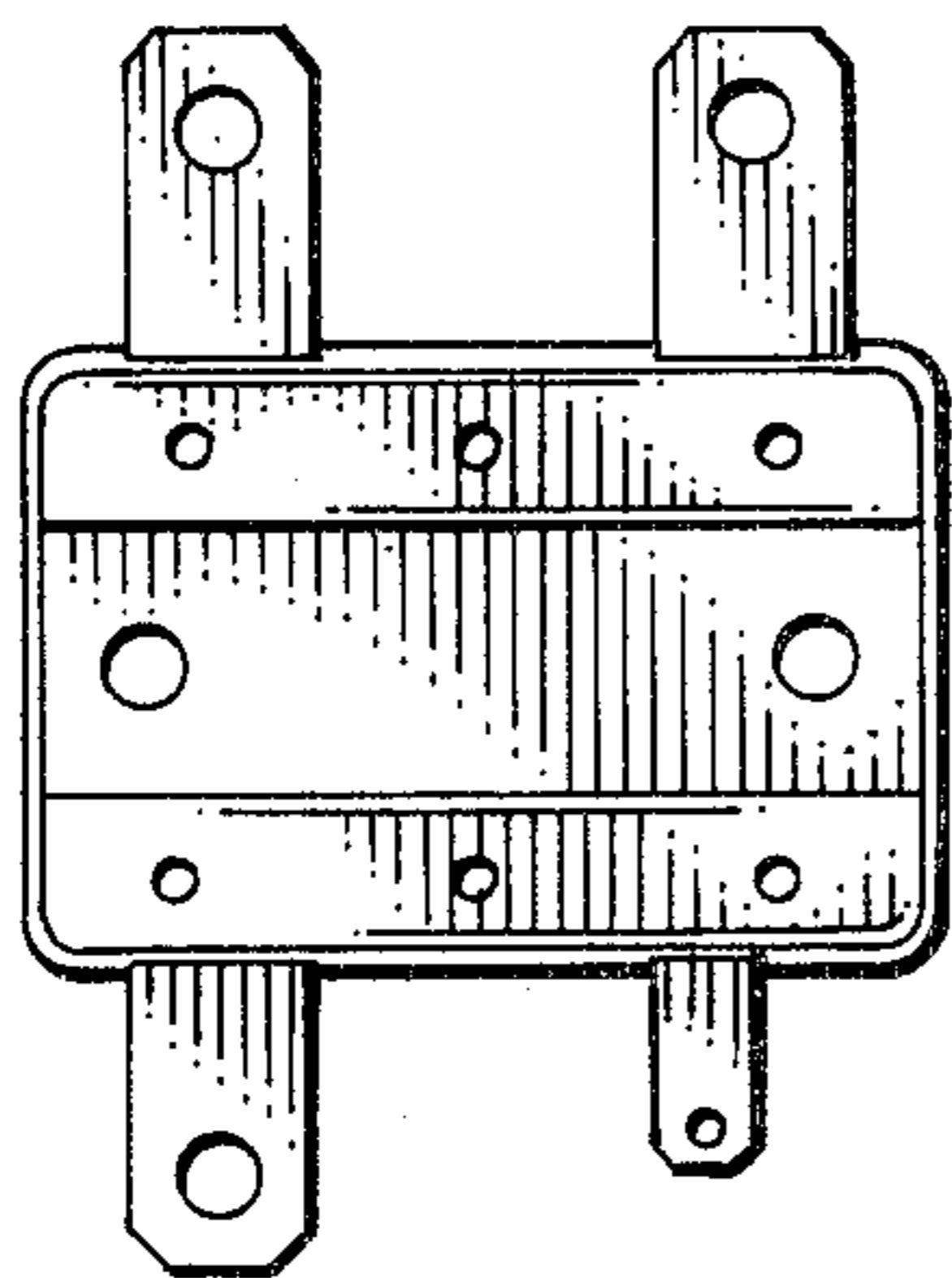


FIG. 18

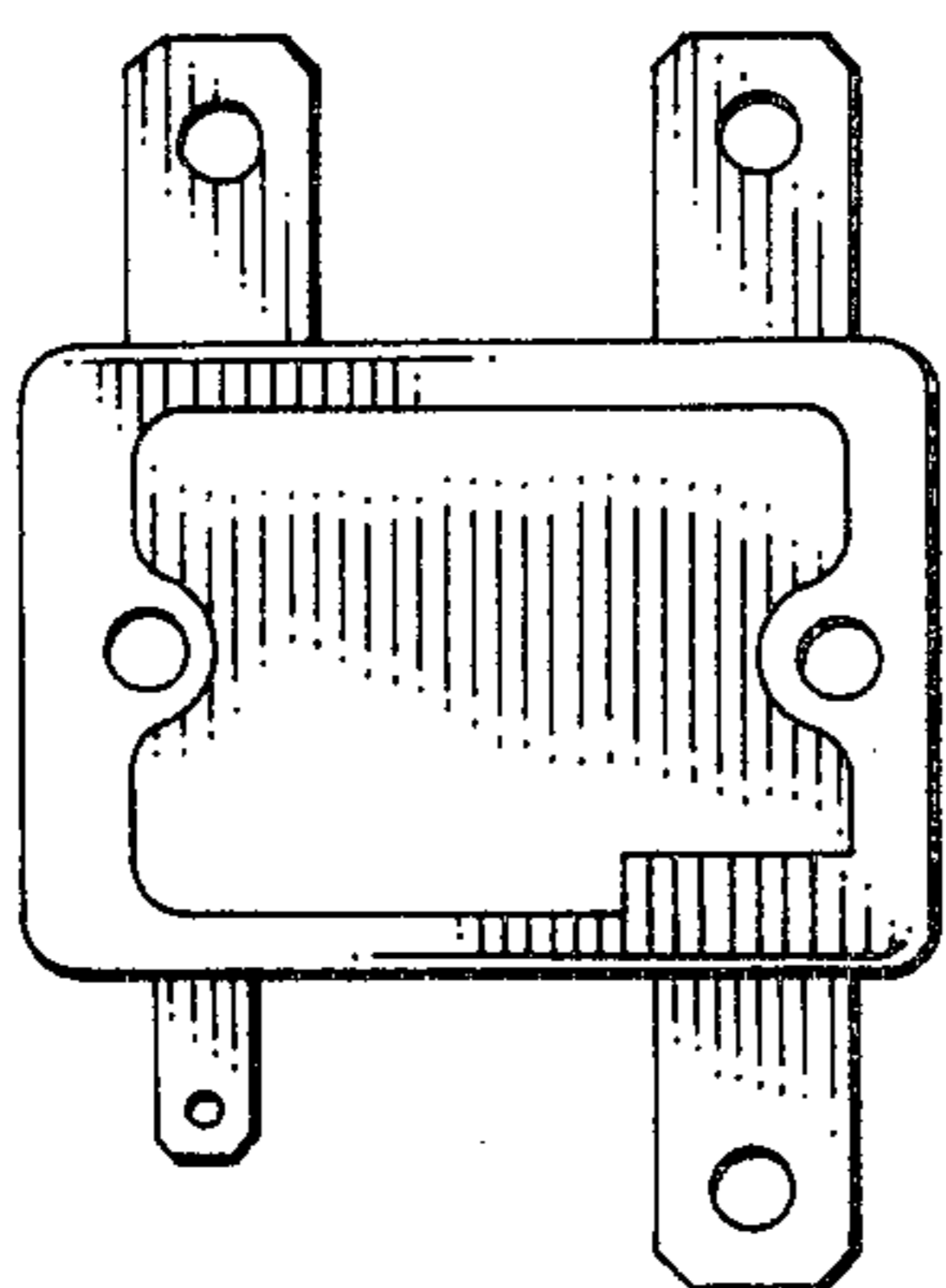


FIG. 19

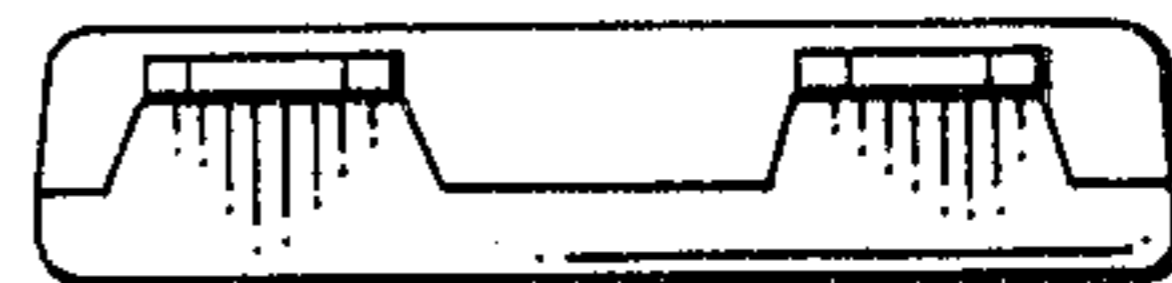


FIG. 20

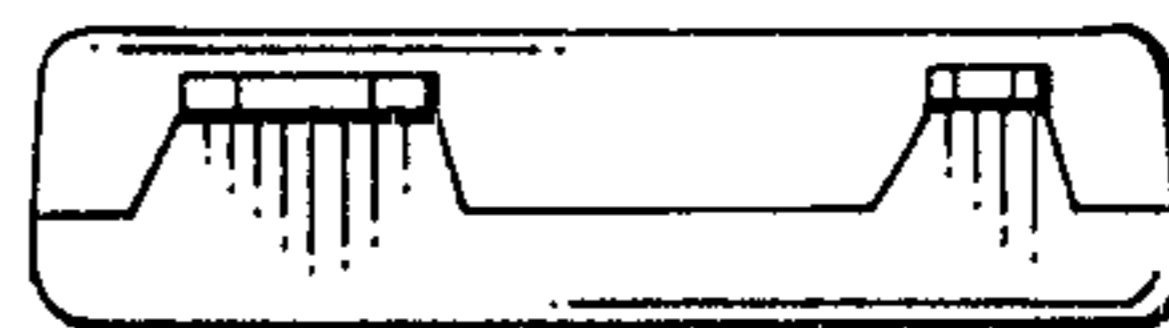


FIG. 21